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Thick Film Chip Dividers, High Voltage





LINKS TO ADDITIONAL RESOURCES

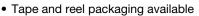




FEATURES

- High voltage up to 3000 V
- Typical resistance ratios of 250:1 to a maximum resistance ratio of 500:1









FREE

- Termination style: 3-sided wraparound termination or single termination flip chip available
- Suitable for solderable, epoxy bondable, or wire bondable applications
- Termination material: solder-coated nickel barrier or solder coated non-magnetic terminations standard; gold, palladium silver, platinum gold, platinum silver or platinum palladium gold terminations available
- Multiple styles, termination materials and configurations, allow wide design flexibility
- Epoxy bondable or wire bondable non-magnetic terminations available
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

Note

* This datasheet provides information about parts that are RoHS-compliant and/or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

STANDARD ELECTRICAL SPECIFICATIONS							
GLOBAL MODEL	CASE SIZE	POWER RATING P _{70 °C} W	MAXIMUM WORKING VOLTAGE ⁽¹⁾ V	RESISTANCE RANGE ⁽²⁾ Ω	TOLERANCE (3) ± %	TEMPERATURE COEFFICIENT ⁽⁴⁾ (-55 °C to +155 °C) ± ppm/°C	TCR TRACKING ± ppm/°C
CDHV 2512	2512	1	3000	20M to 20G	1, 2, 5, 10, 20	100	50 (typical)

Notes

- (1) Continuous working voltage shall be $\sqrt{P \times R}$ or maximum working voltage, whichever is less
- (2) Resistance values below 1 G Ω are calibrated at 100 V $_{DC}$, and values of 1 G Ω and above are calibrated at 1000 V $_{DC}$. Calibration at other voltages available upon request
- (3) Contact factory for tighter tolerances
- (4) Reference only: not for all values specified. Consult factory for your value

VOLTAGE AND TEMPERATURE COEFFICIENTS OF RESISTANCE CHART TYPICAL					
RESISTANCE (Ω)	RATIO (TYPICAL)	VCR (ppm/V)	TCR (ppm/°C) -55 °C to +155 °C		
20M	250:1	10	100		
150M	300:1	10	150		
800M	500:1	10	200		

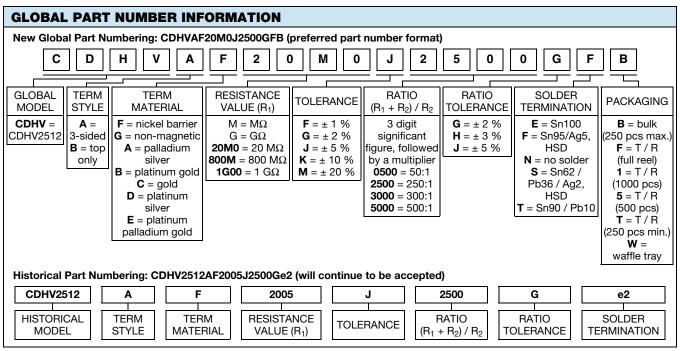
Note

· Contact factory for other ratios

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Note

For additional information on packaging, refer to the "Surface Mount Resistor Packaging" document (www.vishay.com/doc?31543)

MATERIAL SPECIFICATIONS			
Resistive element	Ruthenium oxide		
Encapsulation	Glass		
Substrate	96 % alumina		
Termination	Solder-coated nickel barrier or solder coated non-magnetic terminations standard. Gold, palladium silver, platinum gold, platinum silver, platinum palladium gold terminations available		
Solder finish	Pure tin or tin / lead solder alloys standard. Tin / silver or tin / lead / silver solder alloys available.		

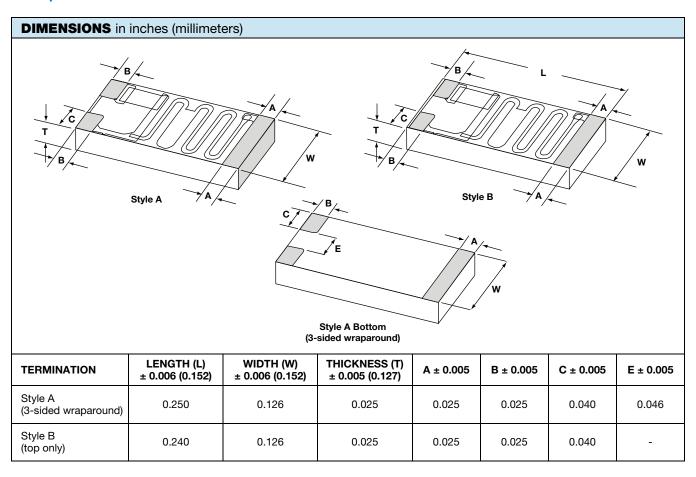
ENVIRONMENTAL SPECIFICATIONS				
Operating temperature	-55 °C to +155 °C			
Life	Less than 0.5 % change when tested at full rated power			

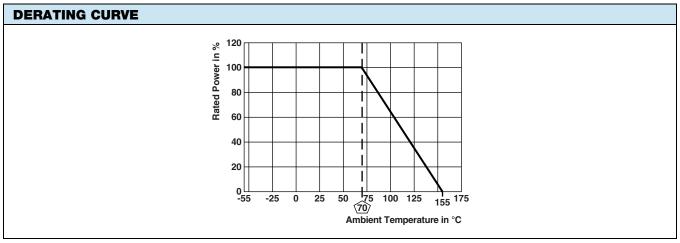
Note

· Reference only: not for all values specified. Consult factory for your size and value

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Note

• Reference only: not for all values specified. Consult factory for your specific value



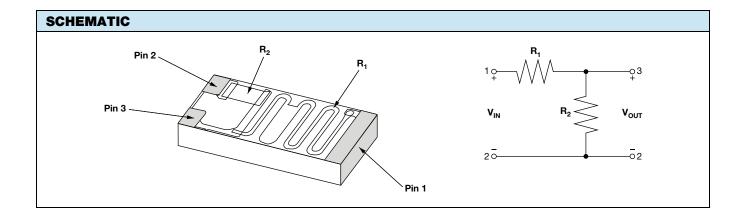
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TYPE	TERMINATION MATERIAL	TERMINATION STYLE	TERMINATION STYLE / MATERIAL CODE	SOLDER TERMINATION CODE	
Solderable	Nickel barrier	3-sided (wraparound)	AF	E or T (standard);	
Solderable	Nickei Damei	Top only (flip chip)	BF	F or S (optional) (1)	
Solderable	Non magnetic	3-sided (wraparound)	AG	E or T (standard);	
	Non-magnetic	Top only (flip chip)	BG	F or S (optional) (1)	
Epoxy bondable / solderable	Platinum palladium gold	Top only (flip chip)	BE	N (standard); F or S (optional) ⁽²⁾	
Wire bondable / epoxy bondable	Gold	Top only (flip chip)	BC	N	
	Palladium silver (3)		BA		
Epoxy bondable	Platinum gold	Top only (flip chip)	BB	N	
	Platinum silver		BD		

Notes

- (1) Standard solder plating for the nickel barrier and non-magnetic parts is solder terminations E or T. Hot solder dipped terminations F or S are also available
- (2) Use solder termination N for applications requiring epoxy bondable mounting, and solder terminations F or S for applications requiring solderable mounting
- (3) While not recommended, palladium silver terminations could be used for solderable applications when using a solder alloy containing silver. If the solder paste being used to solder the palladium silver terminated parts to the boards does not have a silver-based composition, then the silver in the terminations could begin to leach when it is exposed to liquidus non-silver-based solders, causing the potential for solderability and/or solder joint issues



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